



SOT619-14

HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1 mm body

31 August 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220 VKKD-2
Mounting method type	S (surface mount)
Issue date	02-02-2016
Manufacturer package code	98ARE10709D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
package height	-	1	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm body

2 Package outline

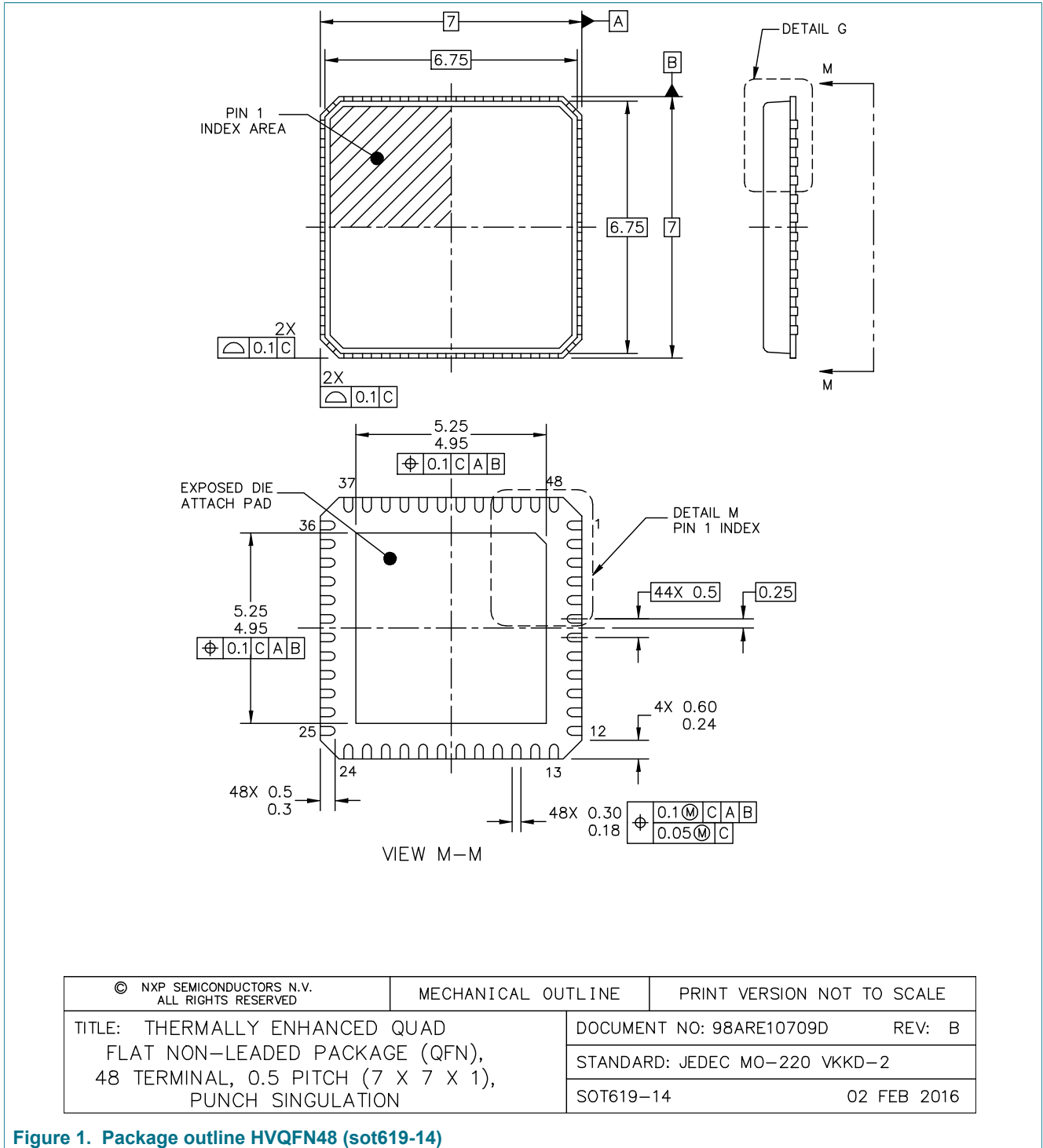
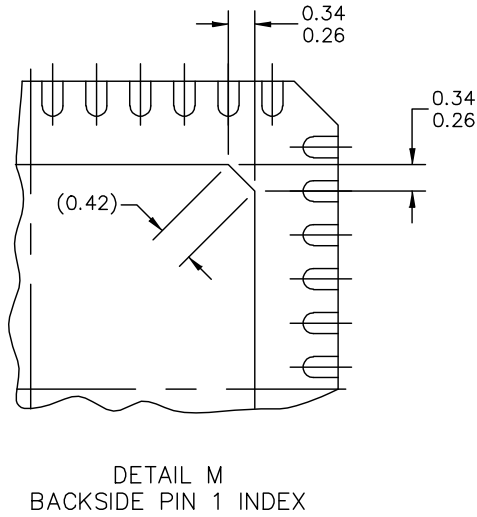
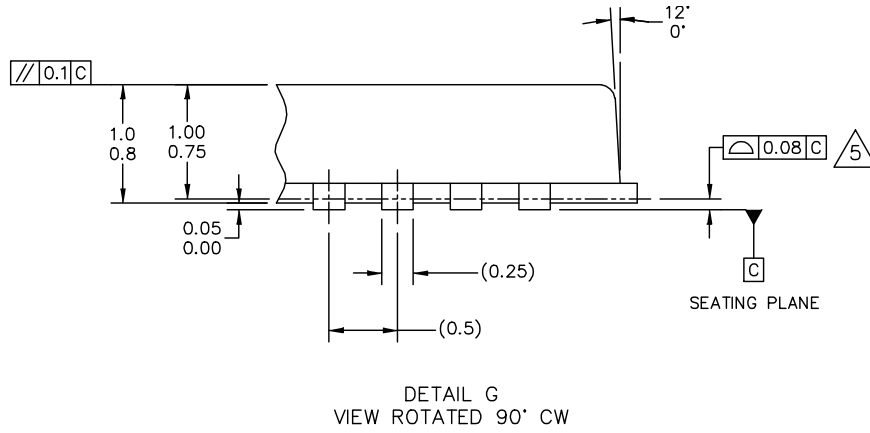


Figure 1. Package outline HVQFN48 (sot619-14)

HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1 mm body




© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN), 48 TERMINAL, 0.5 PITCH (7 X 7 X 1), PUNCH SINGULATION	DOCUMENT NO: 98ARE10709D	REV: B
	STANDARD: JEDEC MO-220 VKKD-2	
	SOT619-14	02 FEB 2016

Figure 2. Package outline dt1 HVQFN48 (sot619-14)

HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4. MOLD SURFACE ROUGHNESS IS 0.8~1.0m(Ra).
5.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
6. FOR ANVIL SINGULATED QFN PACKAGES, MAXIMUM DRAFT ANGLE IS 12°.
7. MIN METAL GAP SHOULD BE 0.25MM.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN), 48 TERMINAL, 0.5 PITCH (7 X 7 X 1), PUNCH SINGULATION	DOCUMENT NO: 98ARE10709D	REV: B
	STANDARD: JEDEC MO-220 VKKD-2	
	SOT619-14	02 FEB 2016

Figure 3. Package outline note HVQFN48 (sot619-14)

HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1 mm body

3 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1 mm body

Contents

1 Package summary1
2 Package outline2
3 Legal information5